Gel-Pak®

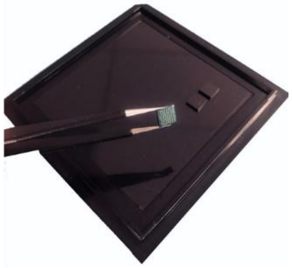
Protecting the World's Valuable Devices

VERTEC® BUMPED DIE CARRIER FILM (GP-BMP3E)

Preliminary Product Datasheet

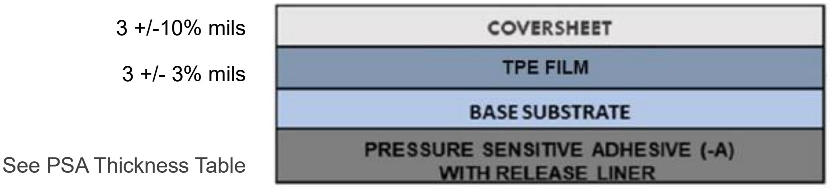
- For bumped die, flip chip and BGA handling.
- Protects fragile solder bumps during handling and transport.
- Flat film surface able to hold bumped devices "bump side down" and easily release.
- Compatible with automated pick & place equipment.
- Can be provided in multiple carrier form factors such as JEDEC standard trays, 2", 4" Trays, flat matrix or customer specific substrates.
- ESD version (static dissipative TPE technology).
- Available in sheet and roll format.

White PSA



Black PSA

Properties	Value
Compatible Device Bump Height	60µm to 160µm
Elastomer Color	Translucent*
Surface Resistance	< 10^{11} (ohms)
Shipping/Storage Temperature	-10 to +50° C
Shelf Life	2 Years
Unique Features	Silicone Free
Printed Grid	Available Upon Request



Pressure Sensitive Adhesive (PSA) Thickness Table

PSA Type	Nominal Thickness
White (Standard)	5.0 mils
Black (Optional)	8.1 mils

* Elastomer Color is translucent, but the surface appearance will depend upon the pressure sensitive adhesive color. White pressure sensitive adhesive is standard and Black is an option. Note: White based PSA BMP material allows for printed location grids. These values are for reference purposes only and are not intended for use in preparing specifications.

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